

IN THE CLAIMS

Please amend the claims as follows:

1. (Currently Amended) A resistive element, comprising:
a first contact point connected to a ground terminal of an integrated circuit bypass capacitor; ~~terminal;~~
a second contact point connected to a circuit board ground plane; and
a resistive material connected to the first and second contact points, wherein a summed series resistance ~~provided~~ obtained by adding a value of resistance ~~for~~ of the resistive element, ~~[[to]] a value of an effective series resistance of [[a]] the bypass capacitor including the bypass capacitor terminal, a value of an equivalent circuit resistance between a power supply voltage terminal of the bypass capacitor and a power supply voltage terminal of a power supply decoupling capacitor located nearest to the bypass capacitor, and a value of an effective resistance between the second contact point and a ground terminal of the power supply decoupling capacitor is approximately equal to an effective series resistance of [[a]] the power supply decoupling capacitor.~~ circuit board and the circuit board plane.
2. (Original) The resistive element of claim 1, wherein the first contact point is connected to the capacitor terminal using solder, and wherein the second contact point is connected to the circuit board plane using at least one via.
3. (Original) The resistive element of claim 1, wherein the resistive material includes a first metal.
4. (Original) The resistive element of claim 3, wherein the first metal is nickel.
5. (Original) The resistive element of claim 3, wherein the resistive material includes a second metal.

6. (Original) The resistive element of claim 5, wherein the second metal is gold.
7. (Original) The resistive element of claim 6, wherein the first and second metals have a width of about 10 to about 1000 microns, a length of about 10 to about 5000 microns, and a total thickness of about 0.05 to about 2.5 microns.
8. (Withdrawn) The resistive element of claim 1, wherein the resistive material includes a conductive epoxy.
9. (Withdrawn) The resistive element of claim 1, wherein the resistive material includes a resistive component selected from a group consisting of: a metal, a conductive metal oxide, a glass, a solvent, a polymer, nickel, chromium, tantalum, oxynitride, silicon monoxide, cobalt, alumina, sapphire, quartz, berillium, palladium, carbon, platinum, ruthenium, rhodium, and gold.
10. (Original) The resistive element of claim 1, wherein the second contact point is connected to the circuit board plane using a plurality of vias.

Claims 11. – 26. (Canceled)

27. (Currently Amended) An apparatus, including:
a circuit element including [[a]] an integrated circuit bypass capacitor; and
a resistive element including a first contact point connected to a ground terminal of the bypass capacitor, a second contact point connected to a circuit board ground plane, and a resistive material connected to the first and second contact points, wherein a summed series resistance ~~provided~~ obtained by adding a value of resistance ~~for~~ of the resistive element, [[to]] a value of an effective series resistance of [[a]] the bypass capacitor including the bypass capacitor terminal, a value of an equivalent circuit resistance between a power supply voltage terminal of the bypass capacitor and a power supply voltage terminal of a power supply decoupling capacitor located nearest to the bypass capacitor, and a value of an effective resistance between the second

contact point and a ground terminal of the power supply decoupling capacitor is approximately equal to an effective series resistance of [[a]] the power supply decoupling capacitor circuit board and the circuit board plane.

28. (Withdrawn) The apparatus of claim 27, wherein the resistive material includes a conductive epoxy and a resistive component selected from a group consisting of: a metal, a conductive metal oxide, a glass, a solvent, a polymer, nickel, chromium, tantalum, oxynitride, silicon monoxide, cobalt, alumina, sapphire, quartz, berillium, palladium, carbon, platinum, ruthenium, rhodium, and gold.
29. (Withdrawn) The apparatus of claim 27, wherein the circuit element includes at least one transistor.
30. (Previously Presented) The apparatus of claim 27, further including:
an outside surface to which the resistive element is attached.
31. (Canceled)
32. (Previously Presented) The apparatus of claim 27, wherein the resistive material includes a first metal.
33. (Previously Presented) The apparatus of claim 32, wherein the first metal is nickel.
34. (Previously Presented) The apparatus of claim 32, wherein the resistive material includes a second metal.
35. (Previously Presented) The apparatus of claim 34, wherein the second metal is gold.